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# FlipChip International Appoints Fred Hickman III as VP Sales & Marketing

PHOENIX, Arizona, January 4, 2006---FlipChip International LLC announced today that it has appointed Fred Hickman III as Vice President of Sales and Marketing for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona. Fred was promoted from Senior Director at FlipChip International (FCI) and Fred will have global FCI responsibility. Fred's background is extensive and includes over 18 years of senior management experience in marketing and sales directly to OEM and IDM customers with a focus on high speed interconnect products and materials. Fred has also held significant leadership roles in management, Product Development and Process Engineering at Westinghouse Electric Corporation, Hadco (Sanmina), Digital Equipment Corporation (HP), and Park Electrochemical Corporation. Fred has a BS degree in Chemistry from the University of South Carolina and is an active member of the IPC and IMAPS interconnect organizations.

Bob Forcier, President and CEO of FlipChip International, stated, "Fred's promotion to the role of VP of Sales & Marketing is perfect timing for the opportunities in 2006 and beyond in the FlipChip International team. Fred's proven successful track record in design wins with OEMs and IDMs will accelerate FCI's growth in the flip chip bumping and the wafer level packaging arena. Fred has excellent senior management and leadership skills that will provide the next level of support to our valued FCI customers. We are fortunate to have Fred provide the leadership of our global sales and marketing efforts."

"I am excited about the opportunity to be a part of FlipChip's strong growth in bumping and wafer level packaging. The market shift to more functionality in wireless portable devices and radio-on-chip applications will continue to fuel the market movement towards flip chip solutions for our semiconductor customers. We also see a strong interest in our licensing portfolio for next generation products and technologies as the market continues toward more lead-free and fine pitch packaging," said Fred Hickman, FCI VP Sales & Marketing.

FlipChip International, LLC is privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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